



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Hui Ou-Yang et al.

SERIAL NO.: 10/080,882

FILED: February 20, 2002

FOR: HIGH DENSITY PLASMA POST-ETCH
TREATMENT FOR A DIELECTRIC
ETCH PROCESS

§ GROUP ART UNIT: 1763

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EXAMINER: A. W. Olsen

Attorney Docket No.:
AM-3467.C1

Date: February 6, 2004

AMENDMENT "B" UNDER 37 CFR § 1.111

**Hon. Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450**

Sir:

This Amendment "B" is in response to the Office Action mailed October 7, 2003, having a shortened statutory period for response of January 7, 2004. A Petition for a One Month Extension of Time to respond to the Office Action accompanies this Amendment "B", to extend the time for response through February 9, 2004.

Claims 1 - 18 are pending in the application.

CERTIFICATE OF MAILING UNDER 37 CFR § 1.10

I hereby certify that this paper is being deposited with the U.S. Postal Service on the date shown below with sufficient postage as U.S. EXPRESS MAIL NO. ER534274121US in an envelope addressed to: Mail Stop Amendment (With Fee), Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Date: February 9, 2004


Shirley L. Church, Reg. No. 31,858

Claims 1 - 6, 9, 11, and 12 are rejected under 35 USC § 102(e) as being anticipated by U.S. Patent No. 6,248,149, to Li et al.

Claims 1 - 18 are rejected under 35 USC § 102(a) as being anticipated by U.S. Patent No. 6,082,374, to Huffman et al.

Claims 1 - 4, 6, 9, and 11 are rejected under 35 USC § 103(a) as being unpatentable over U.S. Patent No. 6,194,128, to Tao et al., in view of U.S. Patent No. 6,036,878, to Collins.

Claims 1 - 4, 6, and 9 - 12 are rejected under 35 USC § 103(a) as being unpatentable over U.S. Patent No. 5,849,639, to Molloy et al.

Please amend the application as follows: